

# SN54CBT16209, SN74CBT16209A 18-BIT FET BUS-EXCHANGE SWITCHES

SCDS006O – NOVEMBER 1992 – REVISED NOVEMBER 2004

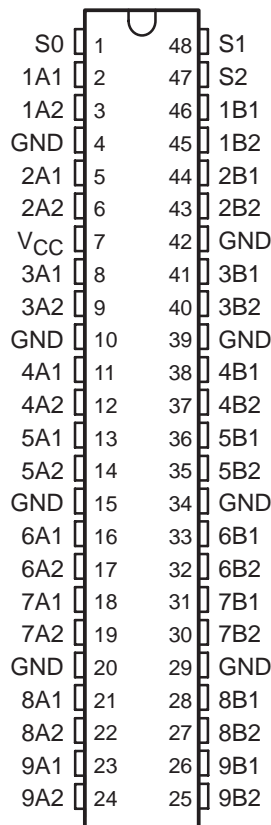
- Members of the Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

## description/ordering information

The SN54CBT16209 and SN74CBT16209A devices provide 18 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switches allows connections to be made with minimal propagation delay.

The devices operate as an 18-bit bus switch or a 9-bit bus exchanger, which provides data exchanging between the four signal ports via the data-select (S0, S1, S2) terminals.

SN54CBT16209 . . . WD PACKAGE  
SN74CBT16209A . . . DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74CBT16209ADL	CBT16209A
		Tape and reel	SN74CBT16209ADLR	
	TSSOP – DGG	Tape and reel	SN74CBT16209ADGGR	CBT16209A
-55°C to 125°C	TVSOP – DGV	Tape and reel	SN74CBT16209ADGVR	CY209A
	CFP – WD	Tube	SNJ54CBT16209WD	SNJ54CBT16209WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54CBT16209, SN74CBT16209A

## 18-BIT FET BUS-EXCHANGE SWITCHES

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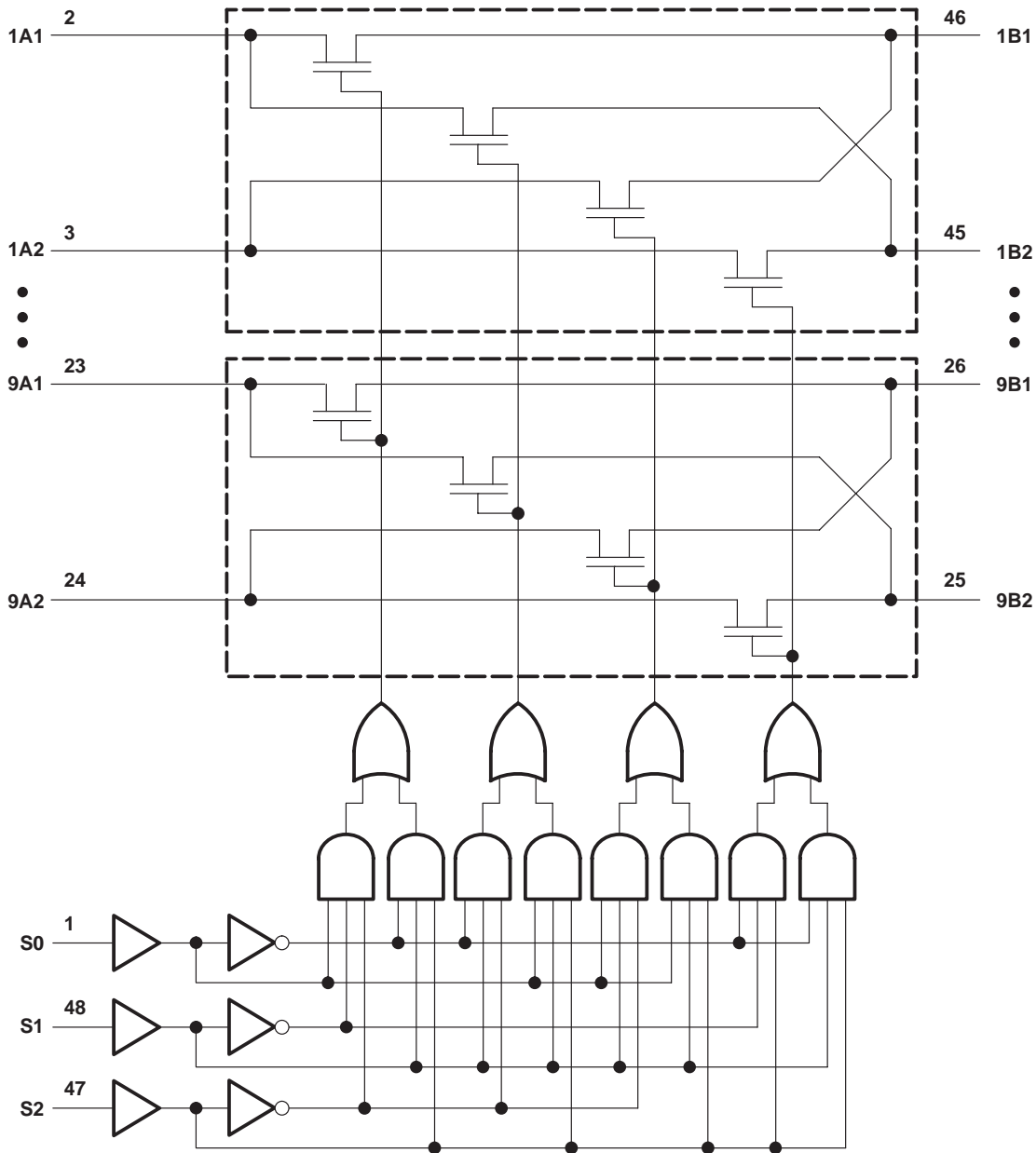
FUNCTION TABLE

INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	Z	Z	Disconnect
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port

# SN54CBT16209, SN74CBT16209A 18-BIT FET BUS-EXCHANGE SWITCHES

SCDS0060 – NOVEMBER 1992 – REVISED NOVEMBER 2004

logic diagram (positive logic)



# SN54CBT16209, SN74CBT16209A 18-BIT FET BUS-EXCHANGE SWITCHES

SCDS0060 – NOVEMBER 1992 – REVISED NOVEMBER 2004

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

		SN54CBT16209		SN74CBT16209A		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4	5.5	4	5.5	V
$V_{IH}$	High-level control input voltage	2		2		V
$V_{IL}$	Low-level control input voltage		0.8		0.8	V
$T_A$	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP <sup>‡</sup>	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			-1.2	V
$I_I$	$V_{CC} = 0$ ,	$V_I = 5.5$ V			10	μA
	$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND			±1	
$I_{CC}$	$V_{CC} = 5.5$ V,	$I_O = 0$ , $V_I = V_{CC}$ or GND			3	μA
$\Delta I_{CC}$ <sup>§</sup>	Control inputs	$V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND			2.5	mA
$C_i$	Control inputs	$V_I = 3$ V or 0			4	pF
$C_{io(OFF)}$	$V_O = 3$ V or 0,	$S_0, S_1, \text{ and } S_2 = \text{GND}$			7.5	pF
$r_{on}$ <sup>¶</sup>	$V_{CC} = 4$ V TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA		14	20	Ω
		$V_I = 0$	$I_I = 64$ mA		4	
	$I_I = 30$ mA			4	8	
	$V_{CC} = 4.5$ V	$V_I = 2.4$ V, $I_I = 15$ mA		6	15	

<sup>‡</sup> All typical values are at  $V_{CC} = 5$  V (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

<sup>¶</sup> Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



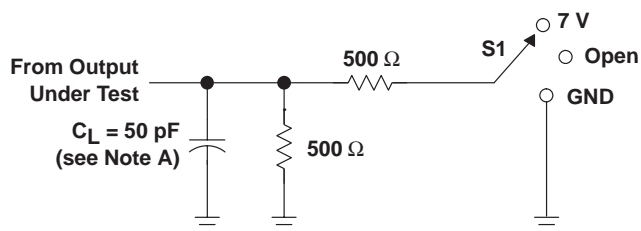
switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBT16209				SN74CBT16209A				UNIT
			$V_{CC} = 4$ V		$V_{CC} = 5$ V $\pm 0.5$ V		$V_{CC} = 4$ V		$V_{CC} = 5$ V $\pm 0.5$ V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A			0.8*			0.35			ns
$t_{pd}$	S	A or B	14	2	13.1			9.9	1.5	9	ns
$t_{en}$	S	A or B	16	1.7	15.3			10.3	1.5	9.8	ns
$t_{dis}$	S	A or B	14.5	1	13.2			9.3	1.5	8.8	ns

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

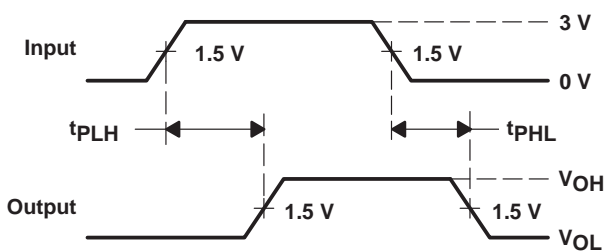
† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION

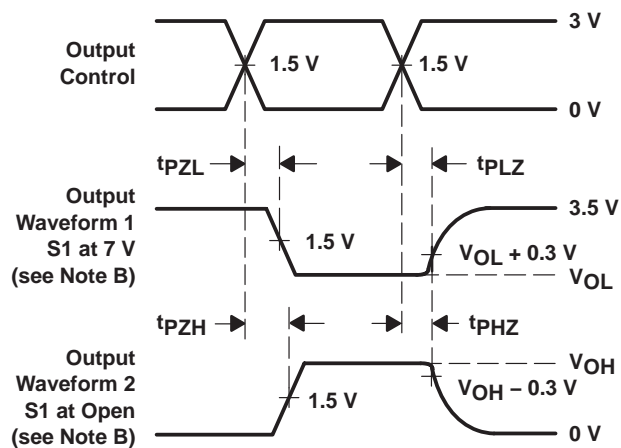


LOAD CIRCUIT

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50$   $\Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9669701QXA	LIFEBUY	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9669701QX A SNJ54CBT16209W D	
74CBT16209ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	<a href="#">Samples</a>
SN74CBT16209ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	<a href="#">Samples</a>
SN74CBT16209ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY209A	<a href="#">Samples</a>
SN74CBT16209ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	<a href="#">Samples</a>
SN74CBT16209ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	<a href="#">Samples</a>
SN74CBT16209ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16209A	<a href="#">Samples</a>
SNJ54CBT16209WD	LIFEBUY	CFP	WD	48	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9669701QX A SNJ54CBT16209W D	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16209ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74CBT16209ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74CBT16209ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16209ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74CBT16209ADGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74CBT16209ADLR	SSOP	DL	48	1000	367.0	367.0	55.0

WD (R-GDFP-F\*\*)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN

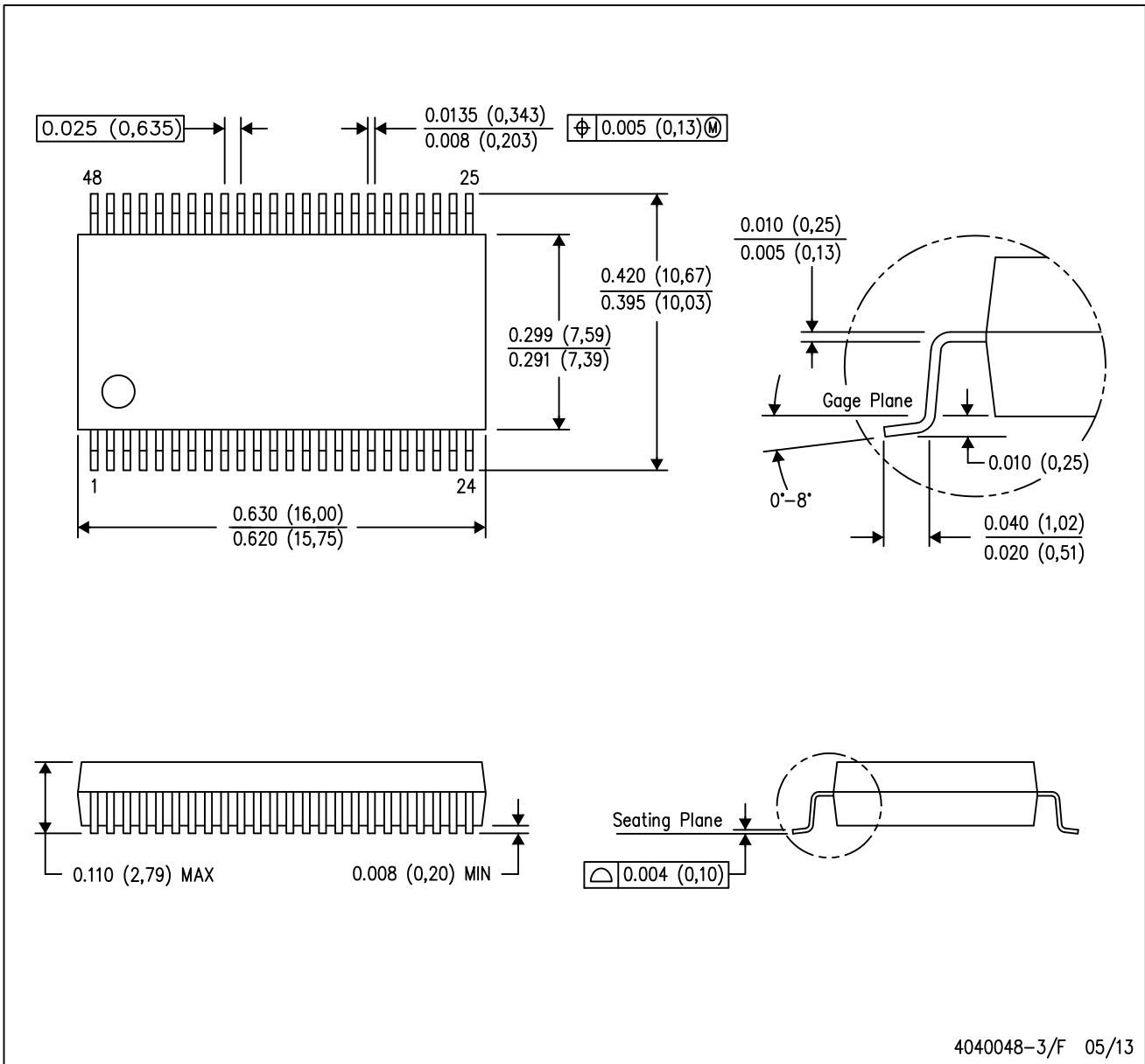


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only  
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA  
 GDFP1-F56 and JEDEC MO-146AB

MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MO-118

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DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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